

Title (en)

BASE MATERIAL FOR CLAD STEEL, CLAD STEEL, AND METHOD FOR MANUFACTURING CLAD STEEL

Title (de)

BASIS MATERIAL FÜR PLATTIERTEN STAHL, PLATTIERTER STAHL UND VERFAHREN ZUR HERSTELLUNG VON PLATTIERTEM STAHL

Title (fr)

MATÉRIAU DE BASE DESTINÉ À DE L'ACIER PLAQUÉ, ACIER PLAQUÉ ET PROCÉDÉ DE FABRICATION D'ACIER PLAQUÉ

Publication

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Application

**EP 20772572 A 20200317**

Priority

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Abstract (en)

A base metal for clad steel contains: in terms of mass%, C: 0.04% to 0.10%, Si: 0.10% to 0.30%, Mn: 1.30% to 1.60%, P: 0.015% or less, S: 0.005% or less, Ni: 0.10% to 0.50%, Cr: 0.10% or less, Cu: 0.05% or less, Mo: 0.05% to 0.40%, V: 0.02% to 0.06%, Nb: 0.03% or less, Ti: 0.005% to 0.025%, Al: 0.020% to 0.050%, N: 0.0030% to 0.0100%, and the balance being Fe and unavoidable impurities. In the composition, a carbon equivalent  $C_{eq}$  according to the following formula (1)  $C_{eq} = C + Mn/6 + (Ni + Cu)/15 + (Cr + Mo + V)/5$  (mass%) is 0.400 or less, and a yield ratio Y.R. according to the following formula (2)  $Y.R. = Y.S. (MPa; 0.5\% \text{ Under load})/T.S. (MPa)$  is less than 0.80.

IPC 8 full level

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